



KMZ49

Magnetic field sensor

Rev. 1 — 31 October 2011

Product data sheet

1. Product profile

1.1 General description

The KMZ49 is a sensitive magnetic field sensor, employing the magnetoresistive effect of thin-film permalloy. The sensor contains two galvanic separated Wheatstone bridges, at a relative angle of 45° to each other.

A rotating magnetic field in the x-y plane will produce two independent sinusoidal output signals, one a function of $+\cos(2\alpha)$ and the second a function of $+\sin(2\alpha)$, α being the angle between sensor and field direction (see [Figure 2](#)). The KMZ49 is suited to high precision angle measurement applications under low field conditions (saturation field strength 25 kA/m).

The sensor can be operated at any frequency between 0 Hz and 1 MHz.

1.2 Features and benefits

- Accurate and reliable angle measurement
- Mechanical robustness, contactless principle
- Wear-free operation
- Accuracy independent of mechanical tolerances
- Extended temperature range

1.3 Applications

- Steering angle and torsion
- Headlight adjustment
- Motor positioning
- Window wipers
- Fuel level
- Mirror positioning

1.4 Quick reference data

Table 1. Quick reference data

$T_{amb} = 25\text{ °C}$; $H_{ext} = 25\text{ kA/m}$; $V_{CC} = 5\text{ V}$; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		[1] -	5	9	V
V_M	peak voltage	see Figure 2	[1][2] 60	67	75	mV
V_{offset}	offset voltage	per supply voltage; see Figure 2	[1] -2	-	+2	mV/V
$TC_{V(offset)}$	offset voltage temperature coefficient	per supply voltage; $T_{amb} = -40\text{ °C}$ to $+150\text{ °C}$; see Figure 2	[1][3] -2	-	+2	($\mu\text{V/V}$)/K
R_{bridge}	bridge resistance		[1][4] 2.7	3.2	3.7	$\text{k}\Omega$

[1] Applicable for bridge 1 and bridge 2.

[2] $V_M = |V_{O(max)} - V_{offset}|$. Periodicity of V_M : $\sin(2\alpha)$ and $\cos(2\alpha)$, respectively.

[3] $TC_{V(offset)} = \frac{V_{offset}(at\ 150\text{ °C}) - V_{offset}(at\ -40\text{ °C})}{150\text{ °C} - (-40\text{ °C})}$

[4] Bridge resistance between pin 4 to pin 8, pin 3 to pin 7, pin 1 to pin 5 and pin 2 to pin 6.

2. Pinning information

Table 2. Pinning

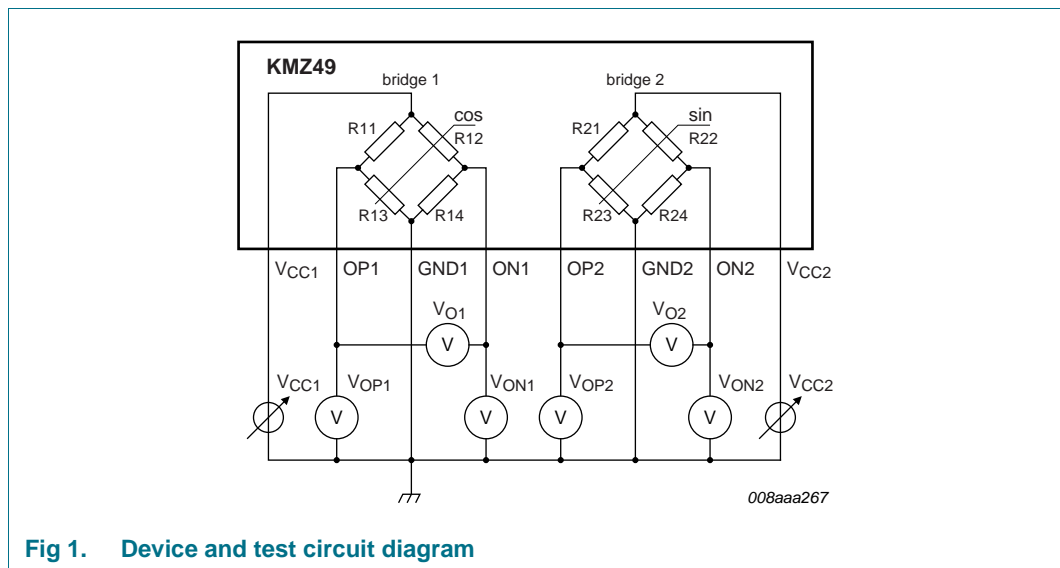
Pin	Symbol	Description	Simplified outline
1	ON1	output voltage bridge 1	
2	ON2	output voltage bridge 2	
3	V_{CC2}	supply voltage bridge 2	
4	V_{CC1}	supply voltage bridge 1	
5	OP1	output voltage bridge 1	
6	OP2	output voltage bridge 2	
7	GND2	ground 2	
8	GND1	ground 1	

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
KMZ49	SO8	plastic small outline package; 8 leads; body width 3.9 mm	SOT96-1

4. Circuit diagram



5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage	[1]	-	9	V
H_{ext}	external magnetic field strength		25	-	kA/m
T_{amb}	ambient temperature		-40	+150	°C
T_{stg}	storage temperature		-65	+150	°C

[1] Applicable for bridge 1 and bridge 2.

6. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient		155	K/W

7. Characteristics

Table 6. Characteristics

$T_{amb} = 25\text{ °C}$; $H_{ext} = 25\text{ kA/m}$; $V_{CC} = 5\text{ V}$; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		[1] -	5	9	V
V_M	peak voltage	see Figure 2	[1][2] 60	67	75	mV
TC_{VM}	peak voltage temperature coefficient	$T_{amb} = -40\text{ °C to }+150\text{ °C}$	[1][3] -0.3	-0.36	-0.42	%/K
R_{bridge}	bridge resistance		[1][4] 2.7	3.2	3.7	k Ω
$TC_{R(bridge)}$	bridge resistance temperature coefficient	$T_{amb} = -40\text{ °C to }+150\text{ °C}$	[1][5] 0.24	0.26	0.29	%/K
V_{offset}	offset voltage	per supply voltage; see Figure 2	[1] -2	-	+2	mV/V
$TC_{V(offset)}$	offset voltage temperature coefficient	per supply voltage; $T_{amb} = -40\text{ °C to }+150\text{ °C}$; see Figure 2	[1][6] -2	-	+2	($\mu\text{V/V}$)/K
$V_{o(hys)}$	hysteresis output voltage	see Figure 3	[1][7] 0	0.05	0.18	%FS
k	amplitude synchronism		[8] 99.5	100	100.5	%
TC_k	amplitude synchronism temperature coefficient	$T_{amb} = -40\text{ °C to }+150\text{ °C}$	[9] -0.01	0	+0.01	%/K
$\Delta\alpha$	angular inaccuracy		[10] 0	0.05	0.1	deg

[1] Applicable for bridge 1 and bridge 2.

[2] $V_M = |V_{O(max)} - V_{offset}|$. Periodicity of V_M : $\sin(2\alpha)$ and $\cos(2\alpha)$, respectively.

$$[3] \quad TC_{VM} = \frac{V_M(at\ 150\text{ °C}) - V_M(at\ -40\text{ °C})}{V_M(at\ 25\text{ °C}) \times (150\text{ °C} - (-40\text{ °C}))}$$

[4] Bridge resistance between pin 4 to pin 8, pin 3 to pin 7, pin 1 to pin 5 and pin 2 to pin 6.

$$[5] \quad TC_{R(bridge)} = \frac{R_{bridge}(at\ 150\text{ °C}) - R_{bridge}(at\ -40\text{ °C})}{R_{bridge}(at\ 25\text{ °C}) \times (150\text{ °C} - (-40\text{ °C}))}$$

$$[6] \quad TC_{V(offset)} = \frac{V_{offset}(at\ 150\text{ °C}) - V_{offset}(at\ -40\text{ °C})}{150\text{ °C} - (-40\text{ °C})}$$

$$[7] \quad V_{o(hys)1} = \left| \frac{V_{O1}(67.5^\circ)135^\circ \rightarrow 45^\circ - V_{O1}(67.5^\circ)45^\circ \rightarrow 135^\circ}{2 \times V_{M1}} \right|$$

$$V_{o(hys)2} = \left| \frac{V_{O2}(22.5^\circ)90^\circ \rightarrow 0^\circ - V_{O2}(22.5^\circ)0^\circ \rightarrow 90^\circ}{2 \times V_{M2}} \right|$$

$$[8] \quad k = \frac{V_{M1}}{V_{M2}}$$

$$[9] \quad TC_k = \frac{k(at\ 150\text{ °C}) - k(at\ -40\text{ °C})}{k(at\ 25\text{ °C}) \times (150\text{ °C} - (-40\text{ °C}))}$$

[10] $\Delta\alpha = |\alpha_{real} - \alpha_{meas}|$; $V_{offset} = 0\text{ V}$; inaccuracy of angular measurement due to deviations from ideal sinusoidal characteristics, calculated from the third and fifth harmonics of the spectrum V_O . For definition of α see [Figure 2](#).

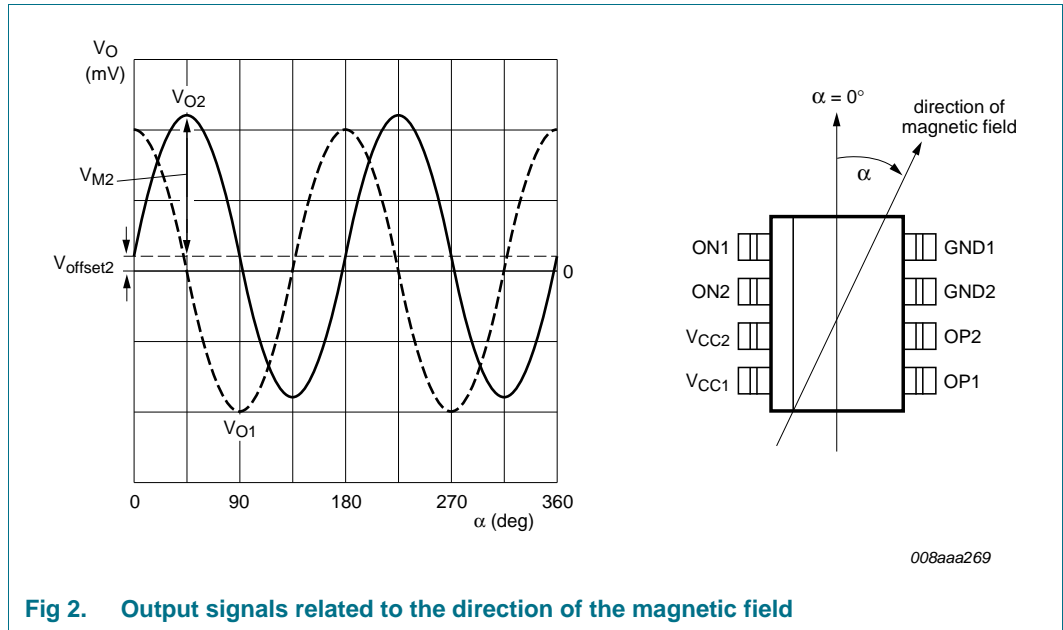


Fig 2. Output signals related to the direction of the magnetic field

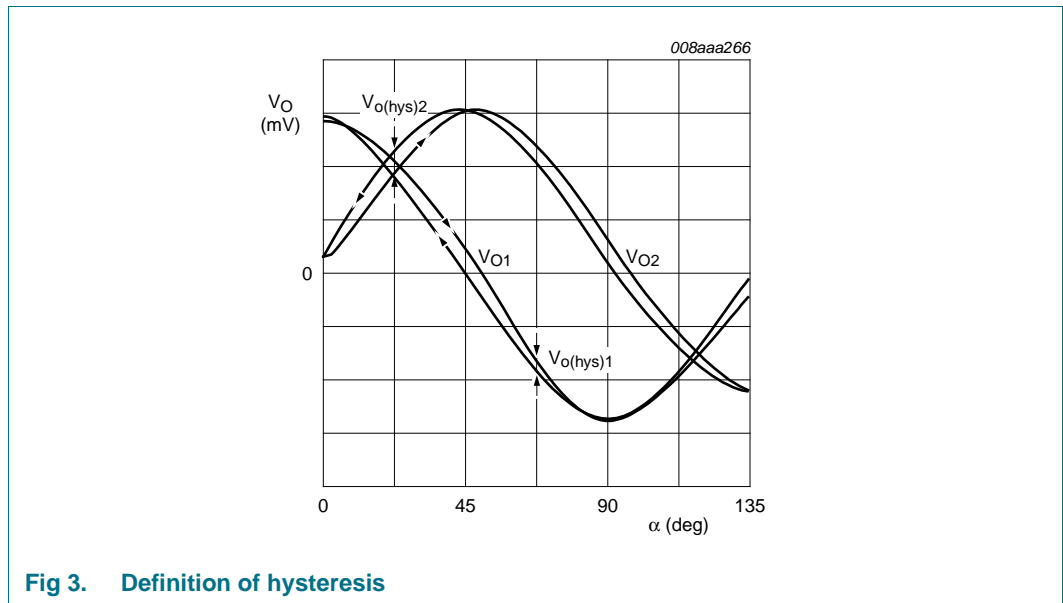


Fig 3. Definition of hysteresis

8. ElectroStatic Discharge (ESD)

8.1 Human body model

The KMZ49 withstands 1 kV, according to the human body model at 100 pF and 1.5 k Ω . The test is according to AEC-Q101, method 001.

9. Test information

9.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

10. Package outline

SO8: plastic small outline package; 8 leads; body width 3.9 mm

SOT96-1

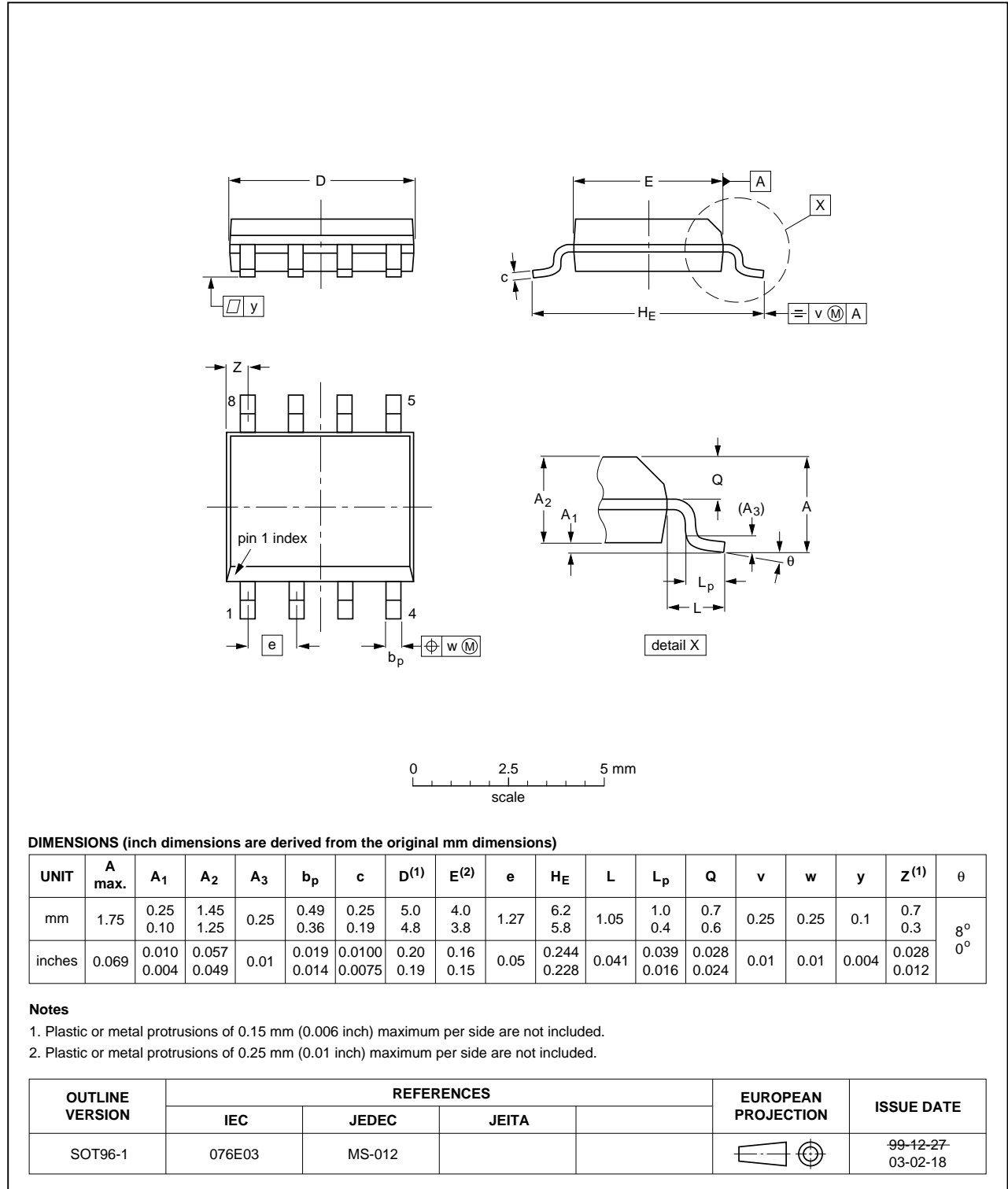


Fig 4. Package outline SOT96-1 (SO8)

11. Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

11.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

11.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

11.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

11.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see [Figure 5](#)) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with [Table 7](#) and [8](#)

Table 7. SnPb eutectic process (from J-STD-020C)

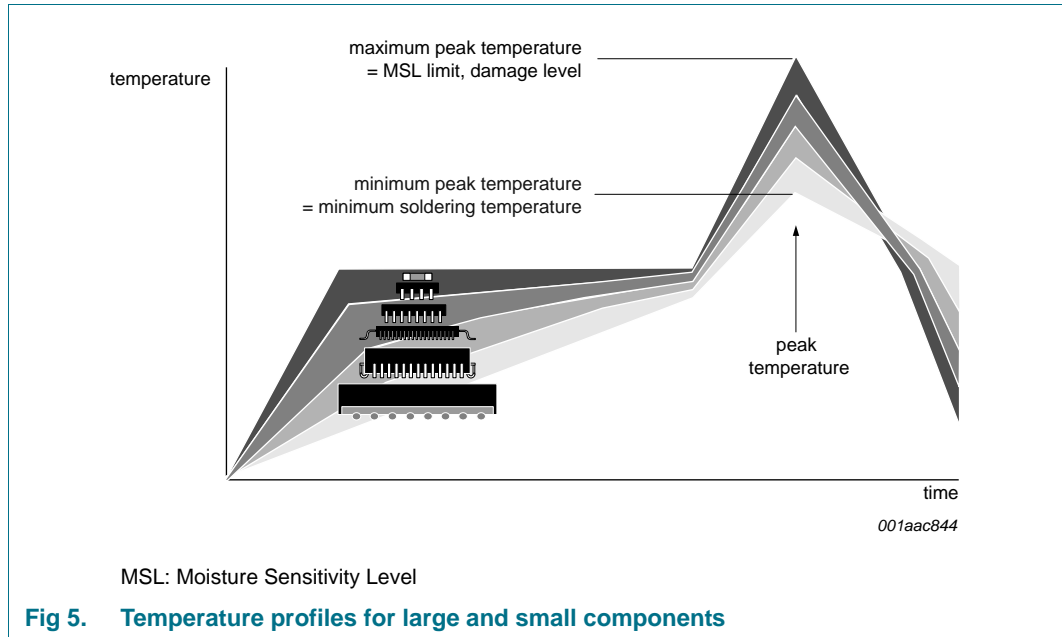
Package thickness (mm)	Package reflow temperature (°C)	
	Volume (mm ³)	
	< 350	≥ 350
< 2.5	235	220
≥ 2.5	220	220

Table 8. Lead-free process (from J-STD-020C)

Package thickness (mm)	Package reflow temperature (°C)		
	Volume (mm ³)		
	< 350	350 to 2000	> 2000
< 1.6	260	260	260
1.6 to 2.5	260	250	245
> 2.5	250	245	245

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see [Figure 5](#).



For further information on temperature profiles, refer to Application Note AN10365 “Surface mount reflow soldering description”.

12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
KMZ49 v.1	20111031	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

13.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

Product specification — The information and data provided in a Product data sheet shall define the specification of the product as agreed between NXP Semiconductors and its customer, unless NXP Semiconductors and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the NXP Semiconductors product is deemed to offer functions and qualities beyond those described in the Product data sheet.

13.3 Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use in automotive applications — This NXP Semiconductors product has been qualified for use in automotive applications. Unless otherwise agreed in writing, the product is not designed,

authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

NXP Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

Terms and conditions of commercial sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nxp.com/profile/terms>, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NXP Semiconductors hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of NXP Semiconductors products by customer.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Quick reference data — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

13.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

14. Contact information

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

15. Contents

1	Product profile	1
1.1	General description	1
1.2	Features and benefits	1
1.3	Applications	1
1.4	Quick reference data	2
2	Pinning information	2
3	Ordering information	2
4	Circuit diagram	3
5	Limiting values	3
6	Thermal characteristics	3
7	Characteristics	4
8	ElectroStatic Discharge (ESD)	6
8.1	Human body model	6
9	Test information	6
9.1	Quality information	6
10	Package outline	7
11	Soldering of SMD packages	8
11.1	Introduction to soldering	8
11.2	Wave and reflow soldering	8
11.3	Wave soldering	8
11.4	Reflow soldering	9
12	Revision history	10
13	Legal information	11
13.1	Data sheet status	11
13.2	Definitions	11
13.3	Disclaimers	11
13.4	Trademarks	12
14	Contact information	12
15	Contents	13

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

© NXP B.V. 2011.

All rights reserved.

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 31 October 2011

Document identifier: KMZ49

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[NXP:](#)

[KMZ49,118](#)